








Micron® MCP Solutions for Embedded Applications

Select from our unique product portfolio of multichip package (MCP) memory solutions that meet your application needs—including extended product lifecycle support, small package sizes, low-power voltage options (1.8V and 1.2V) and extended temperature ranges in select densities.

Micron MCP Packages							
BGA Packages (mm) <i>(package photos are actual size)</i>	121-Ball 8 x 7.5	130-Ball 8 x 9	137-Ball 10.5 x 13	149-Ball 8 x 9.5	162-Ball 8 x 10.5	168-Ball 12 x 12 (PoP)	221-Ball 11.5 x 13
e.MMC + LPDDR3							
8GB e.MMC + 8Gb LPDDR3							✓
e.MMC + LPDDR2							
4GB e.MMC + 4Gb LPDDR2						✓	
NAND + LPDDR4							
4Gb NAND + 4Gb LPDDR4				✓			
4Gb NAND + 2Gb LPDDR4				✓			
NAND + LPDDR3							
4Gb NAND + 8Gb LPDDR3							✓
NAND + LPDDR2							
4Gb NAND + 4Gb LPDDR2					✓		
4Gb NAND + 2Gb LPDDR2					✓		
2Gb NAND + 2Gb LPDDR2					✓		
2Gb NAND + 1Gb LPDDR2					✓		
1Gb NAND + 1Gb LPDDR2	✓						
1Gb NAND + 512Mb LPDDR2	✓						
NAND + LPDDR							
4Gb NAND + 2Gb LPDDR		✓	✓			✓	
2Gb NAND + 1Gb LPDDR		✓	✓				
1Gb NAND + 512Mb LPDDR		✓					

